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Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS
<p>Application Number :</p> <p>Date :</p> <p>First Named Applicant: Leonard J Gardecki</p> <p>Confirmation Number:</p> <p>Attorney Docket Number: BUR920030026US1</p>	
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<p>Submitted By:</p> <p>William D Sabo Registered Number: 27,465</p>	<p>Elec. Sign.</p> <p>William D. Sabo /s/ Attorney</p>

Documents being submitted:	Files
us-fee-sheet	BUR920030026-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	BUR920030026-usidst.xml us-ids.dtd us-ids.xsl
us-request	BUR920030026-usrequ.xml us-request.dtd us-request.xsl
us-assignment	BUR920030026-usassn.xml us-assignment.xsl us-assignment.dtd BUR920030026assignment1.tif BUR920030026assignment2.tif
us-declaration application-body	BUR920030026DEC1.tif BUR920030026-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd BUR20030026drw1.tif BUR20030026drw2.tif BUR20030026drw3.tif BUR20030026drw4.tif BUR20030026drw5.tif BUR20030026drw6.tif

	BUR20030026drw7.tif
	BUR20030026drw8.tif
	BUR20030026drw9.tif
	BUR20030026drw10.tif
	BUR20030026drw11.tif
	BUR20030026drw12.tif
us-declaration	BUR920030026DEC2.tif
us-declaration	BUR920030026DEC3.tif
us-declaration	BUR920030026DEC4.tif
Comments	
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